Material Declaration Report

Package Type:	**N04**
Pericom Package Code:	**TO94-4(Pb-free)**
RoHS Compliance:	**Yes**
Applicable Exemption:	**N/A**

Component Weight (mg):	**155.190**
Termination Plating:	**Matte Tin**
JESD 97 Pb-free Category:	**e3**
Plating Thickness (um):	**10~20**
Tin Whisker Mitigation:	**Anneal, 150C/1hr**

MSL Rating:	**N/A**
Peak Body Temp (C):	**260**
Max Time (sec):	**30**
Reflow Cycles:	**3**
Rev Date:	**Feb.05.2009**

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	49.310	J	Silica Fused	60676-86-0	70.90	34.96079
			Epoxy Resin	29690-82-2	12.50	6.16375
			Phenolic Resin	9003-35-4	8.50	4.19135
			Brominated Resin	Secret	1.50	0.73965
			Carbon Black	1333-86-4	0.55	0.27121
			Wax	Secret	1.25	0.61638
			Flame Retardant	Secret	3.00	1.47930
			Catalyst	Secret	0.50	0.24655
			Stress Absorbent	Secret	0.30	0.14793
			Coupling Agent	Secret	0.50	0.24655
			Releasing Agent.	Secret	0.50	0.24655
LEAD FRAME	100.040		Iron	7439-89-6	0.10	0.10004
			Phosphorus	7723-14-0	0.30	0.30012
			Copper	7440-50-8	98.78	98.81951
			Silver	7740-22-4	0.82	0.82033
TERMINATION PLATING	5.0700		Tin	7440-31-5	99.90	5.06493
			Impurity	Proprietary	0.10	0.00507
SILICON DIE	0.350		Silicon	7440-21-3	99.763	0.34917
			Aluminum(Al)	7429-90-5	0.200	0.00070
			Copper(Cu)	7440-50-8	0.001	0.00000
			Titanium(Ti)	7440-32-6	0.028	0.00010
			Phosphorus(P)	7664-38-2	0.003	0.00001
			Boron(B)	7440-42-8	0.005	0.00002
DIE ATTACH EPOXY	0.335		Silicon Dioxide	14464-46-1	46.25	0.15494
			Epoxy resin	29690-82-2	46.25	0.15494
			Curing Agent and Hardener	Proprietary	7.50	0.02513
GOLD WIRE	0.085		Au	7440-57-5	99.90	0.08492
			Other materials	Proprietary	0.10	0.00009

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

	MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Device	Mold Compound	<2	<2	<2	<2	<5	<5
	Leadframe	<50	<2	<2	<2	<5	<5
	Silicon Die	<2	<2	<2	<2	<5	<5
	Die Attach Epoxy	<2	<2	<2	<2	<5	<5
	Gold Wire	<2	<2	<2	<2	<5	<5
	Solder Plating	<2	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC

and

China RoHS Directive SJ/T11363-2006

Declaration Statement: Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium

Pb <1000ppm	Hg <1000ppm	Cr+6 <1000ppm	Cd <100ppm	PBB <1000ppm	PBDE <1000ppm
O	O	O	O	O	O

O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.
X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.